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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10015374	FILING DATE 12/12/2001	CLASS 257	SUBCLASS 685	GAU 284	EXAMINER <i>Chun S.</i> <i>FL 115</i>
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**APPLICANTS: Oh Kwang; Park Jong; Park Young; Min Byoung;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

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PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed	<input type="checkbox"/> yes <input type="checkbox"/> no	ATTORNEY DOCKET NO	
35 USC 119 conditions met	<input type="checkbox"/> yes <input type="checkbox"/> no		W2K1070
Verified and Acknowledged Examiner's initials			
TITLE : Stacking structure of semiconductor chips and semiconductor package using it			
U.S. DEPT. OF COMM./PAT. & TM-PTO-436L(Rev. 12-94)			

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Prior Office Act O.G.
		Assistant Examiner	
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawn	Fig.s Drawn
		Print Fig.	
TERMINAL			
DISCLAIMER		Primary Examiner	
		PREPARED FOR ISSUE	
		Application Examiner	
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